



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-09-30
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH60RQ06-M2Y	BM6R*2U65Q2A	A	995Y	2020-09-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	8100	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	DM00710594	



Package Designator	Size	Nbr of instances	Shape	
DSO	25 - 23- -5.5	9	gull wing	
Comment	SMITPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.06	die	8
Lead	102.23	soft solder	12621

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	102.23	Soft solder	12621
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	102.228	Soft solder	839993

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BM6R*2U65Q2A					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	31.641	mg	supplier	die	Silicon(Si)	7440-21-3		30.160	mg	953194	3723
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.892	mg	28191	110
				supplier	metallisation	Gold(Au)	7440-57-5		0.013	mg	411	2
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.061	mg	1928	8
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.004	mg	126	0
				supplier	passivation	Silicon oxide	7631-86-9		0.511	mg	16150	63
Leadframe	M-004 Copper and its alloys	779.667	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		778.185	mg	998099	96072
				supplier	alloy & coating	Iron(Fe)	7439-89-6		1.170	mg	1501	144
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.312	mg	400	39
DBC	M-010 Ceramics / glass	2384.165	mg	supplier	metallization	Copper (Cu)	7440-50-8		1725.326	mg	723660	213003
				supplier	ceramic	Aluminum oxide	1344-28-1		632.499	mg	265292	78086
				supplier	ceramic	Magnesium oxide	1309-48-4		26.340	mg	11048	3252
Soft solder	Solder	121.701	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high melting temper	102.228	mg	839993	12621
				supplier	solder	Tin (Sn)	7440-31-5		5.477	mg	45004	676
				supplier	solder	Silver (Ag)	7440-22-4		2.799	mg	22999	346
				supplier	solder	Polyglycol ether	9038-95-3		7.545	mg	61996	931
				supplier	solder	Carboxylic acid	67762-36-1		0.609	mg	5004	75
				supplier	solder	Caster oil	61788-85-0		3.043	mg	25004	376
Bonding wires	M-003 Aluminum and its alloys	28.600	mg	supplier	wire	Aluminium(Al)	7429-90-5		28.600	mg	1000000	3531
Encapsulation	M-011 Other inorganic materials	4736.426	mg	supplier	mold compound	Solid Epoxy Resin	25068-38-6		236.820	mg	50000	29237
				supplier	mold compound	Phenol Resin	29690-82-2		94.730	mg	20000	11695
				supplier	mold compound	Carbon black	1333-86-4		47.365	mg	10000	5848
				supplier	mold compound	Amorphous silica	60676-86-0		4357.511	mg	920000	537964
connections coating	Solder	17.800	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		17.800	mg	1000000	2198